# *MP5496*

**2.8V to 5.5V, Power Management IC with Four 4.5A/2.5A/4A/2A Buck Converters, 5 LDOs, and Flexible System Settings via I <sup>2</sup>C and OTP**

## **DESCRIPTION**

The MP5496 is a complete power management solution that integrates four high-efficiency, stepdown DC/DC converters, five low-dropout (LDO) regulators, and a flexible logic interface.

A DC/DC converter with constant-on-time (COT) control provides fast transient response. The default 1.5MHz fixed switching frequency during continuous conduction mode (CCM) greatly reduces the external inductor and capacitor values. Full protection features include undervoltage lockout (UVLO), over-current protection (OCP), and thermal shutdown.

The output voltage is adjustable through the  $l^2C$ interface, or can be preset by the one-time programmable (OTP) function. The start-up and shutdown sequences can be configured via the OTP.

By using the I <sup>2</sup>C or OTP, the MP5496 can be utilized to configure the buck and LDO output voltages, mode, buck 1 and buck 3 current limits, and the enable function of all the buck converters and LDOs (ENBUCK/LDO).

When using only the I<sup>2</sup>C interface, the MP5496 allows users to configure the buck 2 and buck 4 current limits, slew rate (DVS slew rate), discharge (DISCHG), system enable (SYSEN), and software reset (SFRST). Status and ID2 registers can also be read via the I <sup>2</sup>C.

Additional features, such as AUTOON, frequency, power-on delay, RST delay, pushbutton time, LDORTC output voltage, OTP version, and the I <sup>2</sup>C slave address can only be configured via the OTP.

The MP5496 requires a minimal number of external components, and is available in a space-saving QFN-28 (4mmx4mm) package.

## **FEATURES**

## **Four High-Efficiency Step-Down Converters**

- Buck 1: 4.5A DC/DC Converter
- Buck 2: 2.5A DC/DC Converter
- Buck 3: 4A DC/DC Converter
- Buck 4: 2A DC/DC Converter
- $\bullet$  0.6V to 2.1875V/12.5mV Step V<sub>OUT</sub> Range
- 2.8V to 5.5V Operating Input Range
- Adjustable Switching Frequency
- Configurable Forced PWM, Auto-PFM/PWM Mode
- Hiccup Over-Current Protection (OCP)

### **Five Low-Dropout Regulators**

- One RTC-Dedicated LDO
- Four Low-Noise LDOs
- Two Separate Input Power Supplies
- 100mV Dropout at 300mA Load

### **System**

- $\bullet$ <sup>2</sup>C Bus and OTP
- Power-On/Off Button
- Power-On Reset Output
- Flexible Power-On/Off Sequencing via OTP
- Flexible DC/DC, LDO On/Off via OTP

## **APPLICATIONS**

- Cable Modems, Set-Top Boxes
- Televisions
- Wi-Fi Routers/Access Points
- PoS Machines
- SSDs
- IP Cameras

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## **TYPICAL APPLICATION**

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## **OTP E-Fuse Selected Table by Default (MP5496GR-0001)**



### **Other Parameter Information for the MP5496GR-0001**





## **ORDERING INFORMATION**



\* For Tape & Reel, add suffix –Z (e.g. MP5496GR-XXXX–Z).

\*\* "xxxx" is the configuration code identifier for the register setting stored in the OTP. The default number is "0001". Each "x" can be a hexadecimal value between 0 and F. Work with an MPS FAE to create this unique number, even if ordering the "0001" code. MP5496GR-0001 is the default version.

## **TOP MARKING**

MPSYWW MP5496 LLLLLL

MPS: MPS prefix Y: Year code WW: Week code MP5496: Part number LLLLLL: Lot number



## **EVKT-MP5496 EVALUATION KIT**

EVKT-MP5496 kit contents (items below can be ordered separately):



### **Order directly from MonolithicPower.com or our distributors.**



**Figure 1: EVKT-MP5496 Evaluation Kit Set-Up**

## **PACKAGE REFERENCE**





## **PIN FUNCTIONS**





## **ABSOLUTE MAXIMUM RATINGS**  (1)



## *ESD Ratings*



### *Recommended Operating Conditions*  (3)



### *Thermal Resistance θJA θJC*

#### QFN-28 (4mmx4mm)

JESD51-7 (4) .......................... 44 ........ 9 .... °C/W

#### **Notes:**

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature,  $T_J$  (MAX), the junction-toambient thermal resistance,  $\theta_{JA}$ , and the ambient temperature,  $T_A$ . The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $P_D$  (MAX) = (T<sub>J</sub> (MAX) - TA) /  $\theta_{JA}$ . Exceeding the maximum allowable power dissipation may produce an excessive die temperature, which can cause the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 3) The device is not guaranteed to function outside of its operating conditions.
- 4) Measured on JESD51-7, 4-layer PCB. The value of  $\theta_{JA}$  given in this table is only valid for comparison with other packages and cannot be used for design purposes. These values were calculated in accordance with JESD51-7, and simulated on a specified JEDEC board. They do not represent the performance obtained in an actual application.



## **ELECTRICAL CHARACTERISTICS**

#### **VIN1 = VIN2 = VIN3 = VIN4 = VIN5 = AVIN = 5V, TJ = -40°C to 125°C**  (5) **, unless otherwise noted.**





## **ELECTRICAL CHARACTERISTICS** *(continued)*

#### **VIN1 = VIN2 = VIN3 = VIN4 =VIN5 = AVIN = 5V, TJ = -40°C to +125°C**  (5) **, unless otherwise noted.**





## **ELECTRICAL CHARACTERISTICS** *(continued)*

#### **VIN1 = VIN2 = VIN3 = VIN4 =VIN5 = AVIN = 5V, TJ = -40°C to +125°C**  (5) **, unless otherwise noted.**





## **ELECTRICAL CHARACTERISTICS** *(continued)*

#### **VIN1 = VIN2 = VIN3 = VIN4 =VIN5 = AVIN = 5V, TJ = -40°C to +125°C**  (5) **, unless otherwise noted.**



#### **Notes:**

5) Not tested in production. Guaranteed by over-temperature correlation.

6) Guaranteed by design.

7) VIN2 and VIN4 share the same UVLO threshold. It is recommended to connect VIN2 and VIN4 together in applications.

8) Guaranteed by engineering sample characterization.

9) See the I<sup>2</sup>C Timing Diagram below when reading the I<sup>2</sup>C interface specifications. It is recommended to begin operating the I<sup>2</sup>C after the power-on sequence is finished, or RSTO switches high.



## **I <sup>2</sup>C TIMING DIAGRAM**

**Figure 2: I <sup>2</sup>C Timing Diagram** 

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## **TYPICAL CHARACTERISTICS**

**Performance waveforms are tested on the evaluation board.**  $V_{IN} = 3.3V$ **,**  $T_A = 25^{\circ}C$ **, tested using MP5496GR-0001 specified parts, unless otherwise noted.**













## **TYPICAL PERFORMANCE CHARACTERISTICS**

**Performance waveforms are tested on the evaluation board.**  $V_{IN} = 3.3V$ **,**  $T_A = 25^{\circ}C$ **, tested using MP5496GR-0001 specified parts, unless otherwise noted.**



**Start-Up** 







**Start-Up**   $V_{IN} = 3.3V$ ,  $I_{BUCH} = 4.5A$ 



**Shutdown**   $V_{IN} = 3.3V$ ,  $I_{BUCK1} = 0A$ 









## **TYPICAL PERFORMANCE CHARACTERISTICS** *(continued)*

**Performance waveforms are tested on the evaluation board.**  $V_{IN} = 3.3V$ **,**  $T_A = 25^{\circ}C$ **, tested using MP5496GR-0001 specified parts, unless otherwise noted.**



**Load Transient**   $I_{\text{OUT}} = 2A$  to 4.5A, 2.5A/ $\mu$ s



**nPBIN Start-Up** 





**Load Transient** 



**nPBIN Start-Up**  Each channel with no load



## **nPBIN Shutdown**

Each channel with no load





## **TYPICAL PERFORMANCE CHARACTERISTICS** *(continued)*

**Performance waveforms are tested on the evaluation board.**  $V_{IN} = 3.3V$ **,**  $T_A = 25^{\circ}C$ **, tested using MP5496GR-0001 specified parts, unless otherwise noted.**



**SCP Steady State**  SCP steady state, no load





#### **SCP Recovery**  SCP recovery, no load







**SCP Steady State** 

SCP steady state, full load





## **TYPICAL PERFORMANCE CHARACTERISTICS** *(continued)*

Performance waveforms are tested on the evaluation board.  $V_{IN} = 3.3V$ ,  $T_A = 25^{\circ}C$ , tested using **MP5496GR-0001 specified parts, unless otherwise noted.**





## **FUNCTIONAL BLOCK DIAGRAM**



**Figure 3: Functional Block Diagram**



## **OPERATION**

The MP5496 provides a complete power management solution for many 5V systems, such as televisions, SSDs, and STBs. The MP5496 integrates four high-frequency, synchronous, rectified, step-down switch-mode converters and five low-dropout regulators. The MP5496 greatly reduces PCB space and the number of external components. The MP5496 can manage the power system for either a

### **POWER CONTROL**

#### **State Machine Diagram**

single-cell Li-ion battery or a 5V regulated input voltage, allowing for greater flexibility of the system design.

The I <sup>2</sup>C interface and one-time programmable (OTP) memory interfaces provide an adjustable default output voltage and dynamic voltage scaling. The I <sup>2</sup>C also provides powerful logic functions. See the Register Map section starting on page 27 for more details.



**Figure 4: Power Control State Machine Diagram** 

### **State Machine Description**

Figure 4 shows the state machine, which has multiple features. These features are described below.

### *No Supply*

The PMIC's input pin has an under-voltage lockout (UVLO) detection circuit. If the input voltage (AVIN) is below the UVLO rising threshold, the PMIC's functions are disabled.

### *Power Off*

If AVIN exceeds its rising UVLO threshold and the AUTOON bit  $= 0$ , the PMIC first enters a power-off state. In this state, the PMIC always monitors the power-on factor. Once the poweron factor is detected, the device initiates the power-on sequence.



### *Power-On Sequence*

The DC/DC converters and LDO regulators turn on sequentially according to the preconfigured order via the OTP e-fuse.

### *Power-On*

The DC/DC converters and LDO regulators turn on. The RSTO output switches high. In this state, the PMIC always monitors the power-off or repower-on factors.

### *Power-Off Sequence*

The PMIC enters the power-off sequence if it detects the power-off or repower-on factors while in the power-on state. First RSTO switches low, and then the DC/DC converters and LDO regulators turn off sequentially in the reverse order of the power-on sequence. After the power-off sequence is completed, the repoweron condition (software control) is monitored. Then the PMIC enters the power-on sequence automatically after a delay timer.

#### *Shutdown Event*

If the PMIC detects that the input voltage is below the UVLO falling threshold (the device enters a no supply state) or over-temperature protection is triggered (the device enters a power-off state), the PMIC switches to a no supply state or power-off state, regardless of the current state. (10)

#### **Note:**

10) If PMIC enters a power-off state due to over-temperature protection, LDORTC is off.

### **Power-On Factors**

The PMIC has three power-on factors, described below.

## *SYSEN*

SYSEN is one data bit in the I <sup>2</sup>C register. If the SYSEN bit is set to 1, the system changes from a power-off state and initiates the power-on sequence. Two methods can set SYSEN from 0 to 1. The first method is by setting the AUTOON bit to 1 via the OTP. With this method, the system auto-loads the AUTOON bit into SYSEN when the input voltage exceeds the UVLO threshold. The second method is by using the push button to initiate a power-on sequence.

#### *nPBIN On*

nPBIN on includes two kinds of push-button events. If the nPBIN pin is pulled to logic low (but is not pulled to ground) and asserts low for longer than 2 seconds, the PMIC treats this as a power-on factor. If nPBIN is pulled to ground (below the manual reset threshold) in the poweroff state, and asserts for longer than the maximum 30ms debounce time, the PMIC also treats this as a power-on factor. The SYSEN bit is set high if any of the nPBIN-initiated power-on events described above are detected.

### *Thermal Recovery*

If the MP5496 is in a power-off state because the die temperature has exceeded the thermal protection threshold, the PMIC enters a poweron sequence once the die's temperature decreases.

#### **Power-On Sequence**

There are eight slots for power-on sequence timing (see Figure 5). All the DC/DC converters and LDO regulators (except RTCLDO) can be configured to time slots 0 through 7 by the OTP e-fuse. The delay time between each time slot is related to the default switching frequency of the MP5496 (see Table 1).

#### **Table 1: Slot Time Interval vs. Default Switching Frequency**







**Figure 5: Power-On Sequence (AUTOON Bit is Set to 1)** 

## *OUTRTC On*

The OUTRTC LDO turns on if both VIN2 and AVIN exceed their respective UVLO rising thresholds, regardless of any other pin's status. OUTRTC turns off if either VIN2 or AVIN falls below its respective UVLO falling thresholds, or if thermal shutdown is triggered.

## **Other Buck Regulators and LDOs On**

The MP5496 provides a configurable power-on sequence. If the power-on sequence is fixed, the power-off sequence is reversed. See the OTP Register Description section on page 27 to determine which bits set the time slot number for each channel.

## **Power-Off Factors**

### *nPBIN Long Press*

If nPBIN is pulled to logic low (but not pulled to ground) and asserts longer than 8 seconds, the PMIC enters the power-off sequence.

### *nPBIN Short Press*

If nPBIN is pulled to GND (below the manual reset threshold) and lasts longer than the maximum 30ms debounce time, the PMIC enters the power-off sequence after an 8ms delay time (see Figure 8).

### *SYSEN (Software-Initiated Shutdown)*

The MP5496 supports a software-controlled shutdown through the I <sup>2</sup>C interface. SYSEN is one data bit in the I <sup>2</sup>C register. If the SYSEN bit is set to 0, the system enters a power-off sequence. To restart the PMIC, toggle the input power supply or use the nPBIN function (see the nPBIN Functions section on page 22 for more details).





**Figure 6: Power-Off Sequence via nPBIN Pin Press** 

## **Power-Off Sequence**

RSTO is pulled low before the DC/DC converter or LDO regulator turns off (see Figure 6). The DC/DC converter and LDO regulator power-off sequence is in the reverse order of the power-on sequence.

## **Repower-On Factors**

### *Manual Reset*

To manually reset the device, pull the nPBIN pin to ground (below the manual reset threshold) for longer than the maximum 30ms debounce time. It is released after a set time (see Figure 8).

### *SFRST*

Software reset. If the SFRST bit is set to 1 through the I <sup>2</sup>C interface, the system detects this as a repower-on factor.

#### **Repower-On Sequence (Software-Initiated Power Cycle)**

The MP5496 supports a software-controlled power reset through the I <sup>2</sup>C interface or a manual reset push button.

When using the software-controlled method, the SFRST bit is set high. The MP5496 waits for 8ms and powers off the system, then powers on all of the power rails after a 60ms delay. The SFRST bit is automatically reset to 0 by the RSTO rising edge. After the SFRST bit is reset to 0, the software can control power cycle again. Repower-on factor detection is blocked during the repower-on period (t1 to t2) (see Figure 7).





**Figure 7: Repower-On Sequence (Software Control)** 

If the PMIC is working in a power-on state when using the manual reset control method, and the manual reset button is pressed down, the PMIC enters a power-off sequence. It enters this sequence after a maximum 30ms debounce time and 8ms of delay, then remains in the power-off state until the manual reset button is released. After a 30ms debounce time, the PMIC enters the power-on sequence again, and the manual reset function is also completed (see Figure 8).

## **Shutdown Sequence**

If the input voltage drops below the UVLO falling threshold, or the IC experiences an overtemperature condition, the PMIC immediately enters the shutdown sequence. All DC/DC converters and LDO regulators turn off at the same time (see Figure 9).



**Figure 8: Repower-On Sequence (Manual Reset Control)** 





**Figure 9: Shutdown Sequence** 

## **HIGH-EFFICIENCY BUCK REGULATORS**

Buck 1 to buck 4 are synchronous, step-down DC/DC converters with built-in under-voltage lockout (UVLO), soft start, compensation, and hiccup current limit protection. Fixed-frequency constant-on-time (COT) control provides fast transient response. The switching clock is phase-shifted from buck 1 to buck 4 during continuous conduction mode (CCM). Buck 2 and buck 4 support 100% duty cycle mode.

### **Power Supply and Under-Voltage Lockout (UVLO)**

VIN1 is the power supply for buck 1. VIN2 is the power supply for buck 2, LDORTC, LDO2, and LDO3. VIN3 is the power supply for buck 3. VIN4 is the supply for buck 4. VIN5 is the power supply for LDO4 and LDO5. AVIN is the power input for the biased internal logic blocks.

VIN1, VIN3, VIN5, and AVIN have their own under-voltage lockout (UVLO) thresholds with a proper hysteresis. VIN2 and VIN4 share the same UVLO threshold. If AVIN ramps up and exceeds the UVLO rising threshold, the nPBIN logic is enabled and ready to accept start-up and shutdown commands. LDORTC is active once VIN2 exceeds the rising threshold. Before the power key turns on, the input shutdown current is typically 15µA.

## **Internal Soft Start (SS)**

Soft start (SS) is implemented to prevent the PMIC output voltage from overshooting during start-up. When the PMIC starts up, the internal circuitry of each power rail generates a soft-start voltage that ramps up from 0V. The soft-start

period lasts until the voltage on the soft-start capacitor exceeds the reference voltage. At this point, the reference voltage takes over. For the four buck outputs, their soft-start times are fixed internally at 450µs. For the LDO2-5 outputs, their soft-start times are fixed internally at 70µs. For LDORTC, the soft-start slew rate is always  $35mV/\mu s$ .

### **Output Discharge**

To discharge the energy of the output capacitor during a power-off sequence, there is an active discharge path from the DC/DC converters' and LDO regulators' output to ground. The discharge path turns on when the corresponding channel is disabled. The typical discharge resistance is  $7\Omega$ . The discharge function can be enabled or disabled through the I <sup>2</sup>C interface.

## **SYSTEM CONTROL SIGNALS**

### **nPBIN Functions**

nPBIN is a multi-function pin that supports pushbutton detection and manual reset functions. There is an internal pull-up current to pull up nPBIN's voltage to AVIN. The MP5496 distinguishes between the push-button and manual reset functions by the different pull-low resistances. Connect nPBIN to ground for a manual reset function. Connect nPBIN to ground through a 34kΩ resistor to generate a pushbutton signal (see Figure 10).

A push-button event and manual reset event can both generate an interrupt signal, and set the corresponding interrupt bit high. See the Status 2 register on page 34 for details.





**Figure 10: nPBIN Functional Block Diagram**

## *Push-Button Control*

Long Press 1/Start-Up: If AVIN exceeds the UVLO threshold and the push button asserts low for longer than 2 seconds when the PMIC is in the power-off state, the power-on sequence

begins. The power-on sequence must be completed before the backside CPU can take over control. The power-on sequence must be complete when the RSTO signal switches high (see Figure 11).



### **Figure 11: nPBIN Push-Button Long Press 1 (Start-Up)**

Long Press 2/Shutdown: If the push button asserts low for more than 8 seconds during the power-on state, the power-off sequence begins. The MP5496 turns off all regulators and LDOs (excluding OUTRTC).

The power-off sequence turns off all components in the reverse order of start-up. If nPBIN is pulled low through a 34kΩ resistor at all times, the MP5496 remains in the power-off state (see Figure 12).







### *Manual Reset Control*

Short Press and Release/Manual Reset: If the PMIC is in a power-off state, a short press on nPBIN pulls the nPBIN voltage below the manual reset threshold with a maximum 30ms debounce time, and then the PMIC begins the power-on sequence. When the PMIC is powered on, a short press drops the nPBIN voltage below the manual reset threshold with a maximum 30ms debounce time, and triggers the manual reset function (see Figure 13).



**Figure 13: nPBIN Push Button Short Press to Ground** 

If the manual reset function is triggered, the PMIC turns off and remains off until the manual reset button is released. The PMIC enters the power-on state again after a maximum 30ms debounce time.

## **Automatic Turn-On**

If the AUTOON bit in the OTP configuration table is set high, the system changes the default value of SYSEN to 1. The PMIC enters the power-on sequence automatically once the input voltage (AVIN) exceeds its under-voltage lockout (UVLO) threshold. The system can start up automatically without the push button being pressed. After start-up, the push button can still support the manual power-on and power-off control. SYSEN can be read or written by the I <sup>2</sup>C.

## **RSTO (Reset Output)**

When buck 4's output voltage is ready ( $V_{FB}$ ) exceeds  $90\%$  of  $V_{REF}$ ), RSTO outputs high to enable the processer after an RSTO delay time. RSTO is an open-drain structure with an external pull-up resistor. RSTO is pulled low when buck 4's output is below 80% of the nominal value, or when the system detects a power-off factor, shutdown factor, or repower-on factor.

### **Thermal Warning and Shutdown**

Thermal warning and shutdown prevent the part from operating at exceedingly high temperatures. If the silicon die temperature exceeds 120°C, the MP5496 sets the OTWARNING bit to 1.

If the die temperature exceeds 153°C, the MP5496 sets the OTEMPP bit to 1. Meanwhile, the system enters the shutdown sequence. When the temperature recovers to 130°C, the regulator enters the power-on sequence again.

## **I <sup>2</sup>C Timing Graph**

The I <sup>2</sup>C interface of the PMIC is powered by an internal, fixed, 2V power supply. When VIN exceeds its UVLO threshold during VIN start-up, this 2V power supply is ready after a 0.5ms delay. After another 5ms of delay time, the I<sup>2</sup>C is available (see Figure 14).





### **I <sup>2</sup>C INTERFACE**

#### **I <sup>2</sup>C Serial Interface Description**

The I<sup>2</sup>C is a two-wire, bidirectional, serial interface consisting of a data line (SDA) and a clock line (SCL). The lines are externally pulled to a bus voltage when they are idle. A master device connected to the line generates the SCL signal and device address, and arranges the communication sequence.

The MP5496 interface is an I <sup>2</sup>C slave that supports both fast mode (400kHz) and highspeed mode (3.4MHz). The I <sup>2</sup>C interface adds flexibility to the power supply solution. The output voltage, transition slew rate, and other parameters can be controlled by the I <sup>2</sup>C interface instantaneously. When the master sends the address as an 8-bit value, the 7-bit address should be followed by a 0 or 1 to indicate a write or read operation, respectively.

### **Start and Stop Conditions**

Start (S) and stop (P) conditions are signaled by the master device, which signifies the beginning and end of the I <sup>2</sup>C transfer. The start condition is defined as the SDA signal transitioning from high to low while the SCL is high. The stop condition is defined as the SDA signal transitioning from low to high while the SCL is high (see Figure 15).



**Figure 15: Start and Stop Conditions** 

The master generates the SCL clocks, then transmits the device address and the read/write direction bit (R/W) on the SDA line.

#### **Transfer Data**

Data is transferred in 8-bit bytes by the SDA line. Each byte of data must be followed by an acknowledge (ACK) bit.

#### **I <sup>2</sup>C Update Sequence**

The MP5496 requires a start condition, valid  $l^2C$ address, register address byte, and a data byte for a single data update. The MP5496 acknowledges each byte that has been received by pulling the SDA line low during the high period of a single clock pulse. A valid I <sup>2</sup>C address selects the MP5496. The MP5496 performs an update on the falling edge of the LSB byte. Figure 16, Figure 17, and Figure 18 show examples of I <sup>2</sup>C write and read sequences.







**Figure 18: I 2C Read Example (Read Single Register)** 



## **OTP REGISTER DESCRIPTION**

## **OTP E-Fuse Configuration Table**



### **OTP E-Fuse Selected Table by Default (MP5496GR-0001)**



#### **Other Parameter Information for the MP5496GR-0001**





## **OTP REGISTERS**









## **I <sup>2</sup>C REGISTER MAP**



## **REGISTER DESCRIPTION**

### **I <sup>2</sup>C Bus Slave Address**  (11)

The slave address is 7 bits followed by an 8th data direction bit (read or write). The A3, A2, and A1 bits can be configured via the OTP e-fuse.



#### **Notes:**

11) By default, the slave address is  $0x69$ ,  $A[7:1] = 1101001$ .

12) This bit is configurable via the OTP e-fuse.



## **I <sup>2</sup>C REGISTERS**

## **Reg 00: CTL0**



### **Reg 01: CTL1**



## **Reg 02: CTL2**





### **Reg 03: ILIMIT**



#### **Reg 04 to Reg 0B: VOUTSET and EN**



#### **Table 2: Output Voltage Chart for Buck 1, Buck 2, Buck 3, and Buck 4**





## **MP5496 – 5V, DIGITAL PMIC WITH 9 OUTPUTS**



#### **Table 2: Output Voltage Chart for Buck 1, Buck 2, Buck 3, and Buck 4 (continued)**



## **LDO Regulator Output Voltage Set**



#### **Table 3: Output Voltage Chart of all LDOs**





## **Reg 0D: Status 1**

Status registers are non-latch. This register automatically updates according to its real-time status.



#### **Reg 0E: Status 2**



## **Reg 0F: Status 3**



### **Reg 11: ID2**





## **APPLICATION INFORMATION**

#### **Selecting the Inductor**

For most applications, use a 0.47µH to 2.2µH inductor with a DC current rating at least 25% greater than the maximum load current. For the highest efficiency, use an inductor with a DC resistance below 15mΩ. For most designs, the inductance value can be calculated with Equation (1):

$$
L_1 = \frac{V_{\text{OUT}} \times (V_{\text{IN}} - V_{\text{OUT}})}{V_{\text{IN}} \times \Delta I_L \times f_{\text{OSC}}} \tag{1}
$$

Where  $\Delta I_L$  is the inductor ripple current.

Choose the inductor ripple current to be approximately 30% of the maximum load current. The maximum inductor peak current can be estimated with Equation (2):

$$
I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2}
$$
 (2)

Use a larger inductor (<100mA) to improve efficiency under light-load conditions.

#### **Selecting the Step-Down Converter Input Capacitor**

The step-down converter has discontinuous input current, and requires a capacitor to supply AC current to the converter while maintaining the DC input voltage. Use-low ESR capacitors for the best performance. Ceramic capacitors with X5R or X7R dielectrics are recommended because of their low ESR and small temperature coefficients. For most applications, use a 22µF capacitor.

Since C1 absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in the input capacitor can be estimated with Equation (3):

$$
I_{C1} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \left(1 - \frac{V_{OUT}}{V_{IN}}\right)} \tag{3}
$$

The worst-case condition occurs at  $V_{IN} = 2V_{OUT}$ , calculated with Equation (4):

$$
I_{C1} = \frac{I_{LOAD}}{2}
$$
 (4)

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum, or ceramic. When using electrolytic or tantalum capacitors, add a small, high-quality, ceramic capacitor (e.g. 0.1μF) placed as close to the IC as possible. When using ceramic capacitors, ensure that they have enough capacitance to provide sufficient charge to prevent excessive voltage ripple at the input. The input voltage ripple caused by the capacitance can be estimated with Equation (5):

$$
\Delta V_{IN} = \frac{I_{LOAD}}{f_{SW} \times C1} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \tag{5}
$$

### **Selecting the Step-Down Converter Output Capacitor**

The output capacitor for the step-down regulator maintains the DC output voltage. Use ceramic, tantalum, or low-ESR electrolytic capacitors. For the best results, use low-ESR capacitors to keep the output voltage ripple low. The output voltage ripple can be estimated with Equation (6):

$$
\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{SW}} \times L_1} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times \left(R_{\text{ESR}} + \frac{1}{8 \times f_{\text{SW}} \times C2}\right) \tag{6}
$$

Where  $L_1$  is the inductor value, and  $R_{ESR}$  is the equivalent series resistance (ESR) value of the output capacitor.

For ceramic capacitors, the capacitance dominates the impedance at the switching frequency and causes the majority of the output voltage ripple. For simplification, the output voltage ripple can be estimated with Equation (7):

$$
\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{8 \times f_{\text{SW}}^2 \times L_1 \times C2} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \tag{7}
$$

For tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency. For simplification, the output ripple can be calculated with Equation (8):

$$
\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{SW}} \times L_1} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times R_{\text{ESR}} \tag{8}
$$

The characteristics of the output capacitor also affect the stability of the regulation.

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### **Recommended External Components for DC/DC and LDO Converters**

Table 4 lists recommended external components for the DC/DC converters and LDO regulators.



#### **Table 4: Recommended External Components**



### **PCB Layout Guidelines**  (13)

Efficient PCB layout is critical for stable operation. A 4-layer layout is recommended for the best performance. For the best results, refer to Figure 14 and follow the guidelines below:

- 1. Connect the input ground to GND using the shortest and widest trace possible.
- 2. Connect the input capacitor to VIN using the shortest and widest trace possible.
- 3. Ensure that FB1, FB2, FB3, and FB4 are Kelvin-connected to the buck output capacitors. Do not directly connect FB to the inductor's output node.
- 4. Route SW away from sensitive analog areas, such as FB1 to FB4.

#### **Note:**

13) The recommended layout is based on Figure 20 on page 38.



**Figure 19: Recommended Layout**  (14)

#### **Note:**

14) It is recommended to separate Buck 1/3 and Buck 2/4's PGND on the top layer.



## **TYPICAL APPLICATION CIRCUIT**



**Figure 20: Typical Application Circuit**  (15)

#### **Note:**

15) The minimum input voltage of VIN5 is equal to the maximum nominal output voltage of LDO4 and LDO5.



## **PACKAGE INFORMATION**

**QFN-28 (4mmx4mm)** 



TOP VIEW



**BOTTOM VIEW** 







#### RECOMMENDED LAND PATTERN

#### NOTE:

**1) LAND PATTERNS OF PINS 1, 6, 15, AND 20 HAVE THE SAME LENGTH AND WIDTH. 2) LAND PATTERNS OF PINS 7, 14, 21, AND 28 HAVE THE SAME LENGTH AND WIDTH. 3) ALL DIMENSIONS ARE IN MILLIMETERS. 4) LEAD COPLANARITY SHALL BE 0.10 MILLIMETERS MAX. 5) DRAWING CONFORMS TO JEDEC MO-220. 6) DRAWING IS NOT TO SCALE.**



## **CARRIER INFORMATION**







## **Revision History**



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